【原因、判断要点、发生工序】局部镀金层的边界受到镀金液的侵蚀,减弱了 PSR 与铜层的结合强度而引起的。

[Causes/processes involved/keys to judgment]

The defect is caused by a weakened adhesion of photo solder resist to conductive copper due to the etching of conductor by gold plating solution at the boundary of p localy plated gold deposit.



2-3-2-6 回路欠陥部 SR 不付/ SR 在线路缺陷部位不黏结/ No solder resist on conductor defect

【特徴】回路欠陥部にSRが塗布されていない状態の欠陥

【特征】在线路缺陷部位不能涂布 SR 的缺陷。

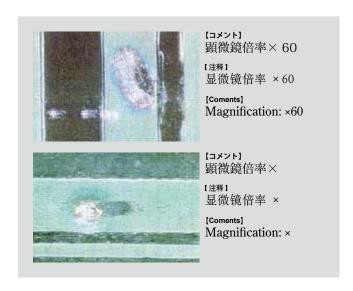
[Characteristics] Solder resist does not coat a conductor defect.

【原因・判断ポイント・発生工程】導体回路の凹凸 欠陥などの部分に、SRインクが塗布されなかった 為に出来たもの(導体回路形成前~SR塗布工程)

【原因、判断要点、发生工序】在线路凹凸缺陷等的部位不能涂布 SR 而引起的(图形转移前~涂布 SR 工序)

[Causes/processes involved/keys to judgment]

The defect is caused by the absence of solder resist ink on an uneven surface of a conductive pattern (Before conductor pattern formation - solder resist application process)



2-3-2-7 SR 静電気むら/SR 因静电而不均匀/ Uneven solder resist surface caused by electrostatic discharge

【特徴】リング状の導体盛り上がり部の内側のSR 厚が薄く、片方の外側SR厚が流星状に厚くなって いる色むら

【特征】在导线的环状鼓起部位 SR 厚度变薄、单向的外侧 SR 厚度变厚,像流星那样颜色深浅不匀。

[Characteristics] Solder resist is thin on the inside of the ring-shaped rising of a conductor pattern and thick in the form of a meteor on one side of the outside of the ring, which makes the colour of solder resist look uneven.



「コメント」 静電気破壊により熔融 した銅がリング状に飛 散してできたダム 顕微鏡倍率×

注释】

由于静电破坏,熔融的铜 环状地飞溅并发生凹陷 显微镜倍率 ×

[Coments]

A dam made by splashing of molten copper by electrostatic discharge in a ring form Magnification: ×